

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
 For capacitive load, derate current by 20%.

Characteristic	Symbol	ES3A/AB	ES3B/BB	ES3C/CB	ES3D/DB	Unit
Peak Repetitive Reverse Voltage	V _{RRM}					
Working Peak Reverse Voltage	V _{RWM}	50	100	150	200	V
DC Blocking Voltage (Note 5)	V _R					
RMS Reverse Voltage	V _{R(RMS)}	35	70	105	140	V
Average Rectified Output Current @ T _T = +100°C	I _O	3.0				A
Non-Repetitive Peak Forward Surge Current 8.3ms	I _{FSM}	100				A
Single Half Sine-Wave Superimposed on Rated Load						

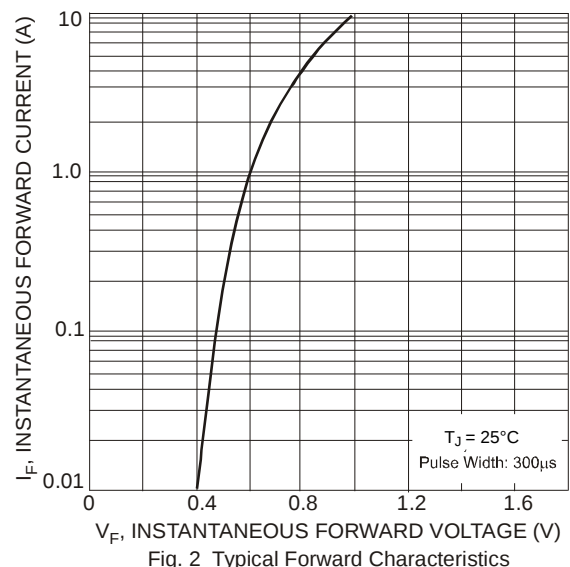
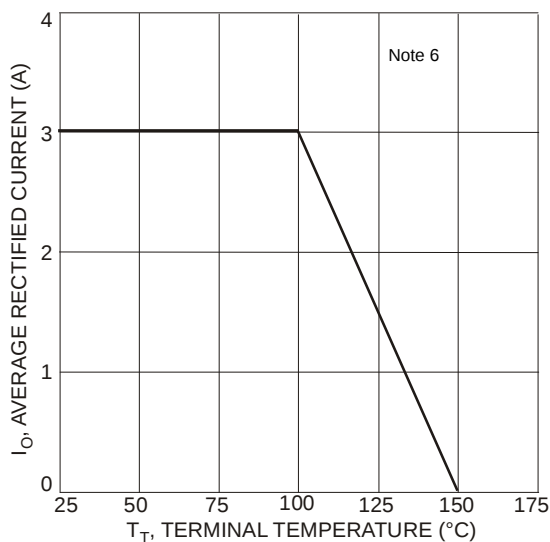
Thermal Characteristics

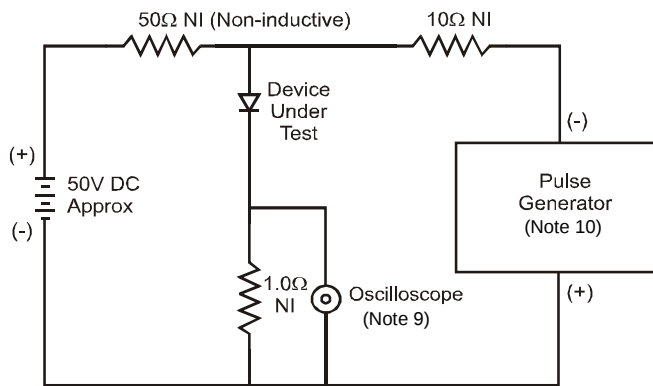
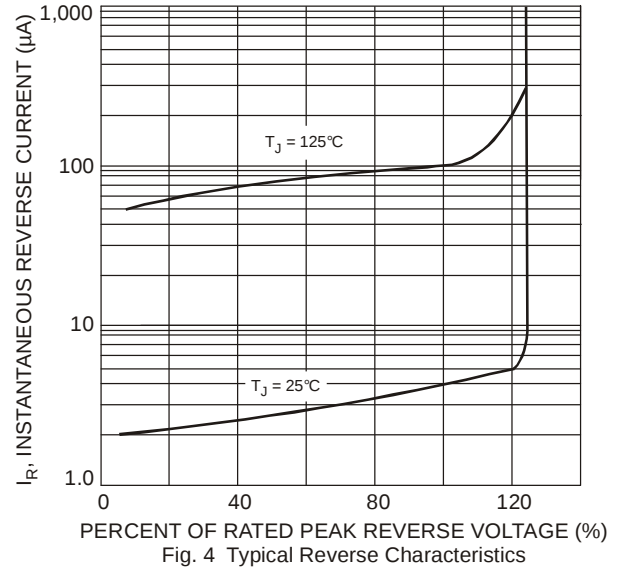
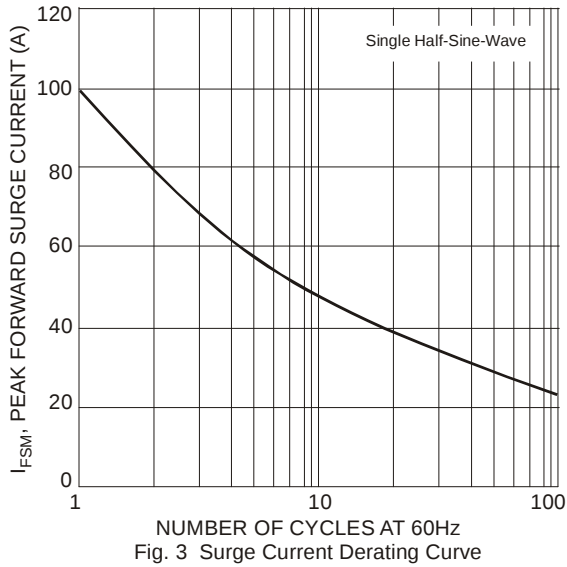
Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal	R _{θJT}	10	°C/W
Typical Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	50	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Maximum Forward Voltage @ I _F = 3.0A	V _{FM}	0.9	V
Peak Reverse Current @ T _A = +25°C	I _{RM}	10	μA
at Rated DC Blocking Voltage (Note 5) @ T _A = +125°C		500	
Maximum Reverse Recovery Time (Note 7)	t _{RR}	25	ns
Typical Total Capacitance (Note 8)	C _T	45	pF

- Notes:
5. Short duration pulse test used to minimize self-heating effect.
 6. Unit mounted on PC board with 5.0 mm² (0.013 mm thick) copper pads as heat sink.
 7. Measured with I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A. See Figure 5.
 8. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.





- Notes:
- Rise Time = 7.0ns max. Input Impedance = 1.0M Ω , 22pF.
 - Rise Time = 10ns max. Input Impedance = 50 Ω .

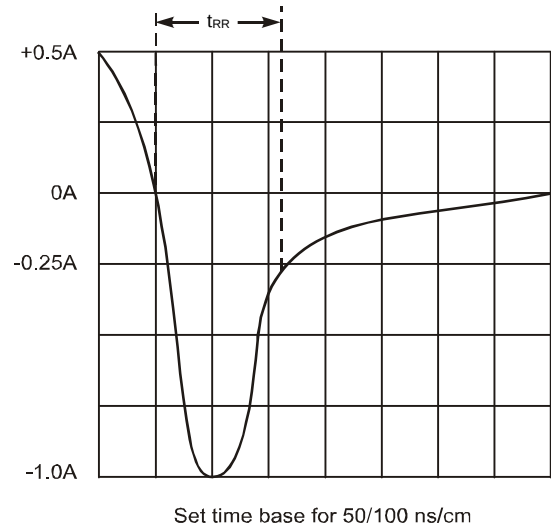
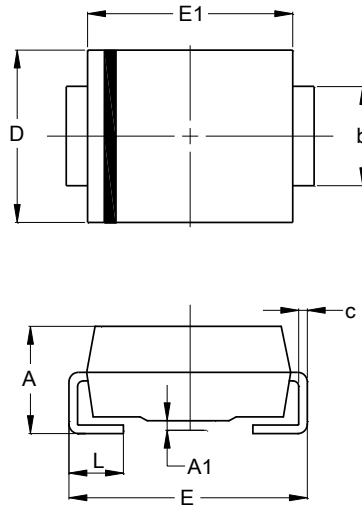


Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

Package Outline Dimensions

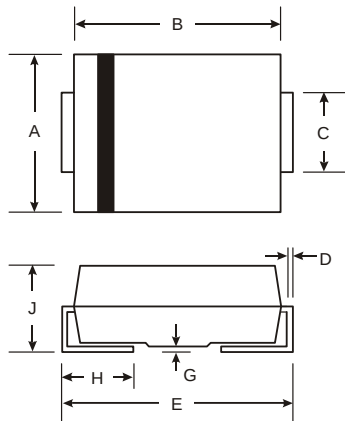
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SMB



SMB		
Dim	Min	Max
A	2.00	2.50
A1	0.05	0.20
b	1.96	2.21
c	0.15	0.31
D	3.30	3.94
E	5.00	5.59
E1	4.06	4.57
L	0.76	1.52
All Dimensions in mm		

SMC

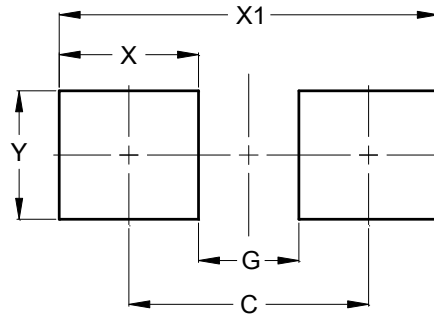


SMC		
Dim	Min	Max
A	5.59	6.22
B	6.60	7.11
C	2.75	3.18
D	0.15	0.31
E	7.75	8.13
G	0.10	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

Suggested Pad Layout

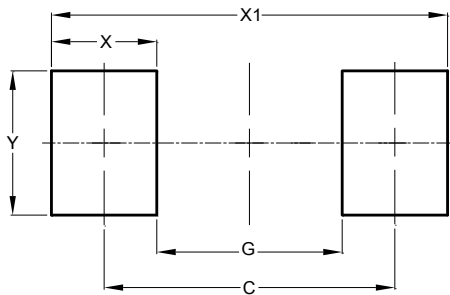
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SMB



Dimensions	Value (in mm)
C	4.30
G	1.80
X	2.50
X1	6.80
Y	2.30

SMC



Dimensions	Value (in mm)
C	6.90
G	4.40
X	2.50
X1	9.40
Y	3.30

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